



## COSMOPLENE® FS3032

### CHARACTERISTICS

COSMOPLENE® FS3032 is Polypropylene Homopolymer resin developed for Biaxially oriented films for dielectric applications used in capacitors.

COSMOPLENE® FS3032 is a high purity resin with low ash content. It does not contain slip, antiblock, nucleating and antistatic additives.

### APPLICATIONS

COSMOPLENE® FS3032 is specially designed for biaxially oriented films for dielectrical films used in capacitors. It is applicable for metallization process.

### PHYSICAL PROPERTIES

ITEM	UNIT	FS3032	TEST METHOD
Melt Flow Rate	g/10 mins	3.0	ASTM D1238
Density	g/cm <sup>3</sup>	0.90	ASTM D792
Melting Point	°C	165	TPC METHOD
Isotactic Index	%	96	TPC METHOD
Catalyst residue, Titanium	ppm	<1	TPC METHOD
Aluminium	ppm	<5	TPC METHOD
Chloride	ppm	<10	TPC METHOD
Total Ash content	ppm	<30	TPC METHOD

- The figures presented are typical laboratory averages, only for reference.
- The information is based on our current knowledge, is subjected to continuous updates and is intended to suggest/recommend product applications and to provide typical data on the related properties. It should not therefore be construed as guaranteeing any specific property of the product. TPC makes no warranty of any kind, expressed or implied, regarding the accuracy of these data.



CERT. NO.: OHS 55006 SEP 2020, SS 506 Part 2: 2013, J. NO.: OHS 2011, BS OHSAS 18001